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(57) **ABSTRACT**

Chip package and method thereof. For example, a chip package of a charging controller chip for a USB charger includes: a high-side transistor including a first drain, a first gate and a first source; a low-side transistor including a second drain, a second gate and a second source, the low-side transistor being connected to the high-side transistor; one or more port transistors corresponding to one or more USB output ports respectively, each port transistor of the one or more port transistors including a third drain, a third gate and a third source; a controller coupled to the high-side transistor, the low-side transistor, and the one or more port transistors; a first chip base; a second chip base electrically insulated from the first chip base; a third chip base electrically insulated from the first chip base and electrically insulated from the second chip base.

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